

HEPCO Model 9400-1 Professional BGA Sphere Placement Equipment



Sphere Diameters from .25mm (.010") - Pitch from .4mm
3-Piece Tooling Kits Available from HEPCO
Vacuum Wand, Flux Stencil and Component Template

Fastest, Most Operator-Friendly System Available
Screen Print No-Clean Tacky Flux
Place Sphere Array
Reflow and Done



HEPCO, Inc. 150 SAN LAZARO AVE., SUNNYVALE, CA 94086 •(408) 738-1880 fax (408) 732-4456
Electronic Component Lead Cut & Form Equipment and BGA Reballing Systems
www.hepcoblue.com

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- 1) Place Cleaned Component
- 2) Screen Print No-Clean Tacky Flux
- 3) Pick Up Spheres
- 4) Place All Spheres At Once
- 5) Remove, Reflow and Done

Patented Pick-Up Method

Places Entire Array At Once

Tooling Pin Alignment

Visual Check Before Placement

New, Patented Backing Plate

Eliminates Clogging

Eliminates Flux Contamination

Optimizes Sphere Release

